



## Material Content Data Sheet



<b>Sales Product Name</b>		ICE3A2065ELJ		<b>Issued</b>		1. August 2018		
<b>MA#</b>		MA000981076						
<b>Package</b>		PG-DIP-8-13		<b>Weight*</b>		557.41 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	4.346	0.78	0.78	7798	7798
leadframe	inorganic material	phosphorus	7723-14-0	0.054	0.01		96	
	non noble metal	zinc	7440-66-6	0.215	0.04		385	
	non noble metal	iron	7439-89-6	4.297	0.77		7709	
wire	non noble metal	copper	7440-50-8	174.475	31.30	32.12	313012	321202
	noble metal	gold	7440-57-5	0.282	0.05	0.05	506	506
	encapsulation	organic material	carbon black	1333-86-4	1.091	0.20		1956
encapsulation	plastics	epoxy resin	-	35.261	6.33		63259	
	inorganic material	silicondioxide	60676-86-0	327.162	58.70	65.23	586937	652152
leadfinish	non noble metal	tin	7440-31-5	7.496	1.34	1.34	13448	13448
plating	noble metal	silver	7440-22-4	0.796	0.14	0.14	1428	1428
glue	plastics	epoxy resin	-	0.290	0.05		520	
	noble metal	silver	7440-22-4	1.642	0.29	0.34	2946	3466
*deviation	< 10%					Sum in total:	100.00	1000000

### Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
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This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

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